

LET20030S

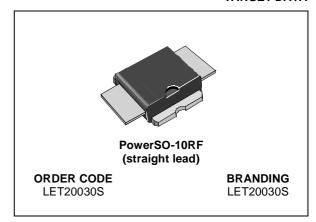
RF POWER TRANSISTORS

Ldmos Enhanced Technology in Plastic Package

TARGET DATA

Designed for GSM / EDGE / IS-97 applications

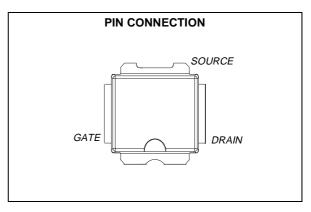
- EXCELLENT THERMAL STABILITY
- COMMON SOURCE CONFIGURATION
- P_{OUT} = 30 W with 11 dB gain @ 2000 MHz
- ESD PROTECTION
- IS-97 CDMA PERFORMANCES
 P_{OUT} = 4.5 W
 EFF = 17 %



DESCRIPTION

The LET20030S is a common source N-Channel, enhancement-mode lateral Field-Effect RF power transistor. It is designed for high gain, broad band commercial and industrial applications. It operates at 26 V in common source mode at frequencies up to 2 GHz. LET20030S boasts the excellent gain, linearity and reliability of ST's latest LDMOS technology mounted in the first true SMD plastic RF power package, PowerSO-10RF. LET20030S's superior linearity performance makes it an ideal solution for base station applications.

The PowerSO-10 plastic package, designed to offer high reliability, is the first ST JEDEC approved, high power SMD package. It has been specially optimized for RF needs and offers excellent RF performances and ease of assembly.



Mounting recommendations are available in www.st.com/rf/ (look for application note AN1294)

ABSOLUTE MAXIMUM RATINGS (T_{CASF} = 25 °C)

Symbol	Parameter	Value	Unit	
V _{(BR)DSS}	Drain-Source Voltage	65	V	
V_{GS}	Gate-Source Voltage	-0.5 to +15	V	
ID	Drain Current	TBD	А	
P _{DISS}	Power Dissipation	140	W	
Tj	Max. Operating Junction Temperature	165	°C	
T _{STG}	Storage Temperature	-65 to +175	°C	

THERMAL DATA

R _{th(j-c)}	Junction -Case Thermal Resistance	1.0	°C/W
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ELECTRICAL SPECIFICATION (T_{CASE} = 25 °C)

STATIC

Symbol	Test Conditions			Min.	Тур.	Max.	Unit
V _{(BR)DSS}	V _{GS} = 0 V	$I_{DS} = 1 \text{ mA}$		65			V
I _{DSS}	V _{GS} = 0 V	V _{DS} = 26 V				1	μΑ
I _{GSS}	V _{GS} = 5 V	V _{DS} = 0 V				1	μΑ
V _{GS(Q)}	V _{DS} = 26 V	I _D = TBD		2.5		5.0	V
V _{DS(ON)}	V _{GS} = 10 V	I _D = 1 A			TBD		V
G _{FS}	V _{DS} = 10 V	I _D = 1 A			TBD		mho
C _{ISS}	V _{GS} = 0 V	V _{DS} = 26 V	f = 1 MHz		TBD		pF
Coss	V _{GS} = 0 V	V _{DS} = 26 V	f = 1 MHz		TBD		pF
C _{RSS}	V _{GS} = 0 V	V _{DS} = 26 V	f = 1 MHz		TBD		pF

Symbol	Te	Min.	Тур.	Max.	Unit		
DYNAMIC $(f = 2000 \text{ MHz})$							
P _{1dB}	$V_{DD} = 26 \text{ V}$ $I_{DQ} = TBD$		30			W	
G _P	$V_{DD} = 26 \text{ V}$ $I_{DQ} = TBD$	P _{OUT} = 30 W	11	13		dB	
ηD	$V_{DD} = 26 \text{ V}$ $I_{DQ} = TBD$	P _{OUT} = 30 W	45	50		%	
IMD3 ⁽¹⁾	$V_{DD} = 26 \text{ V}$ $I_{DQ} = TBD$	P _{OUT} = 30 W PEP		-32	-28	dBc	
Load mismatch	V _{DD} = 26 V I _{DQ} = TBD ALL PHASE ANGLES	P _{OUT} = 30 W			10:1	VSWR	
DYNAMIC (f = 1930 - 1990 MHz)						
P _{OUT} ⁽²⁾	$V_{DD} = 26 \text{ V}$ $I_{DQ} = TBD$		25	30		W	
G _P	$V_{DD} = 26 \text{ V}$ $I_{DQ} = TBD$	P _{OUT} = 30 W	11	13		dB	
$\eta_D^{(2)}$	$V_{DD} = 26 \text{ V}$ $I_{DQ} = TBD$	P _{OUT} = 30 W	40	45		%	
P _{out(CDMA)} ⁽³⁾	885 KHz < -47 dBc 1.25 MHz < -55 dBc 2.25 MHz < -55 dBc			4.5		W	
η _{D(CDMA)} ⁽³⁾	885 KHz < -47 dBc 1.25 MHz < -55 dBc 2.25 MHz < -55 dBc		17		%		

⁽¹⁾ $f_1 = 2000 \text{ MHz}$, $f_2 = 2000.1 \text{ MHz}$

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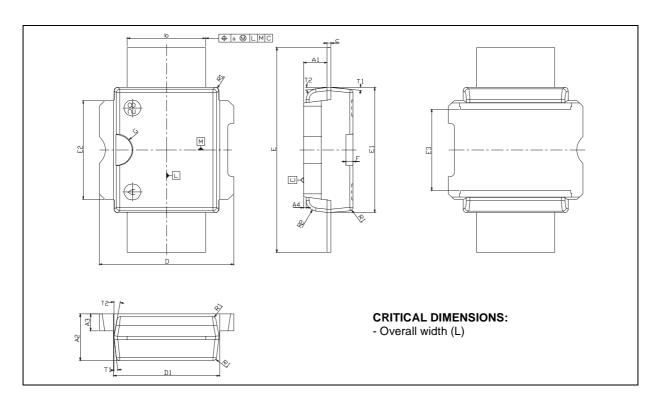
^{(2) 1} dB Compression point

⁽³⁾ IS-97 CDMA Pilot, Sync, Paging, Traffic, Codes 8 Thru 13

PowerSO-10RF Straight Lead MECHANICAL DATA

DIM.	mm			Inch			
	MIN.	TYP.	MAX	MIN.	TYP.	MAX	
A1	1.62	1.67	1.72	0.064	0.065	0.068	
A2	3.4	3.5	3.6	0.134	0.137	0.142	
A3	1.2	1.3	1.4	0.046	0.05	0.054	
A4	0.15	0.2	0.25	0.005	0.007	0.009	
а		0.2			0.007		
b	5.4	5.53	5.65	0.212	0.217	0.221	
С	0.23	0.27	0.32	0.008	0.01	0.012	
D	9.4	9.5	9.6	0.370	0.374	0.377	
D1	7.4	7.5	7.6	0.290	0.295	0.298	
E	15.15	15.4	15.65	0.595	0.606	0.615	
E1	9.3	9.4	9.5	0.365	0.37	0.375	
E2	7.3	7.4	7.5	0.286	0.292	0.294	
E3	5.9	6.1	6.3	0.231	0.24	0.247	
F		0.5			0.019		
G		1.2			0.047		
R1			0.25			0.01	
R2		0.8			0.031		
T1		6 deg			6 deg		
T2		10 deg			10 deg		

Note (1): Resin protrusions not included (max value: 0.15 mm per side)



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